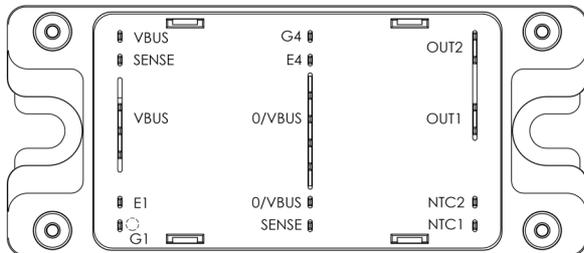
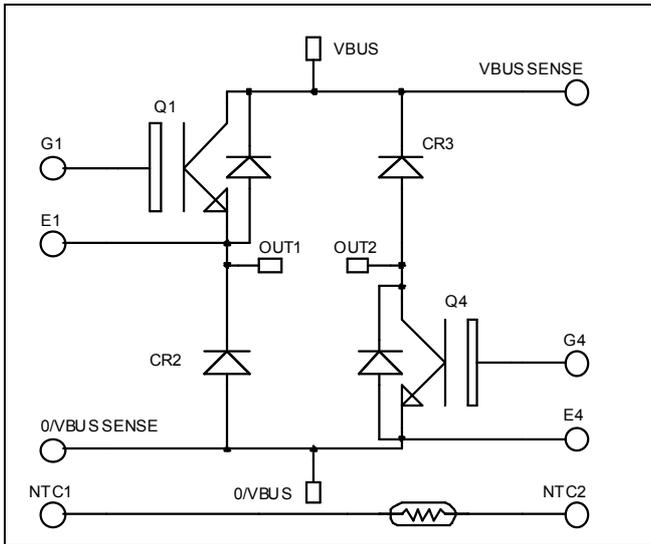


## Asymmetrical - Bridge Trench + Field Stop IGBT3 Power Module

$V_{CES} = 600V$   
 $I_C = 100A @ T_c = 80^\circ C$



### Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

### Features

- Trench + Field Stop IGBT3 Technology
  - Low voltage drop
  - Low tail current
  - Switching frequency up to 20 kHz
  - Soft recovery parallel diodes
  - Low diode VF
  - Low leakage current
  - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- Very low stray inductance
  - Symmetrical design
  - Lead frames for power connections
- Internal thermistor for temperature monitoring
- High level of integration

### Benefits

- Stable temperature behavior
- Very rugged
- Solderable terminals for easy PCB mounting
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive  $T_C$  of  $V_{CESat}$
- Low profile
- RoHS Compliant

### Absolute maximum ratings

Symbol	Parameter	Max ratings	Unit
$V_{CES}$	Collector - Emitter Breakdown Voltage	600	V
$I_C$	Continuous Collector Current	$T_C = 25^\circ C$	150
		$T_C = 80^\circ C$	100
$I_{CM}$	Pulsed Collector Current	$T_C = 25^\circ C$	200
$V_{GE}$	Gate - Emitter Voltage	$\pm 20$	V
$P_D$	Maximum Power Dissipation	$T_C = 25^\circ C$	340
RBSOA	Reverse Bias Safe Operating Area	$T_j = 150^\circ C$	200A @ 550V

**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_{CES}$	Zero Gate Voltage Collector Current	$V_{GE} = 0\text{V}$ , $V_{CE} = 600\text{V}$			250	$\mu\text{A}$
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	$V_{GE} = 15\text{V}$ $I_C = 100\text{A}$		1.5 1.7	1.9	V
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}$ , $I_C = 1.5\text{ mA}$	5.0	5.8	6.5	V
$I_{GES}$	Gate – Emitter Leakage Current	$V_{GE} = 20\text{V}$ , $V_{CE} = 0\text{V}$			400	nA

**Dynamic Characteristics**

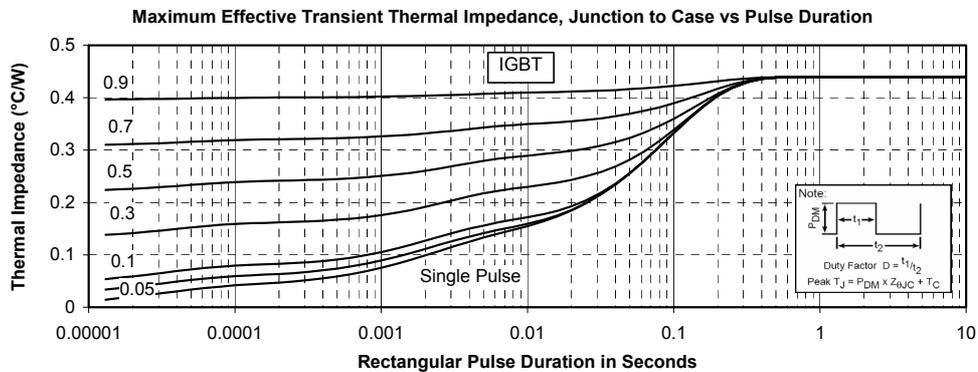
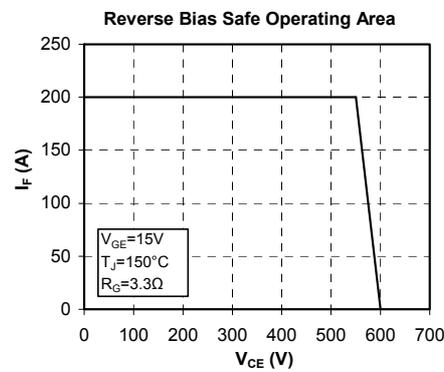
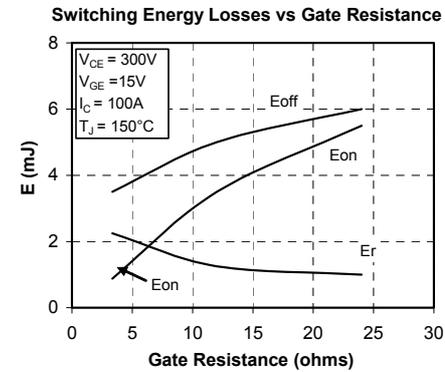
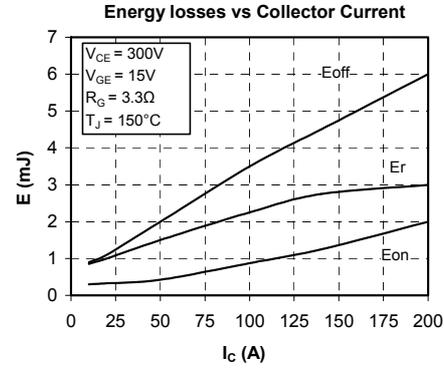
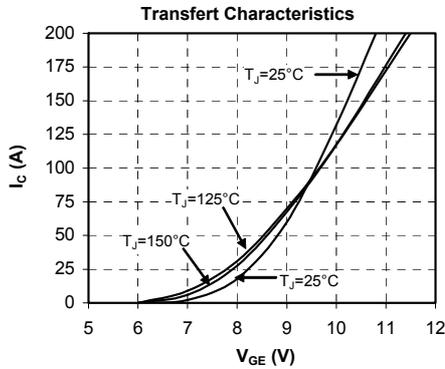
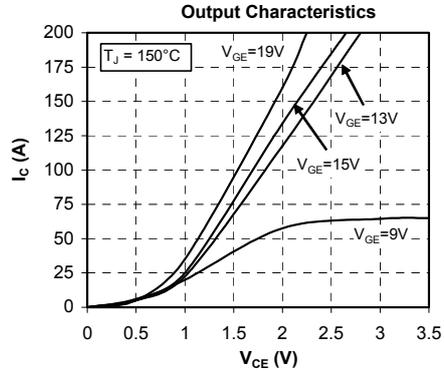
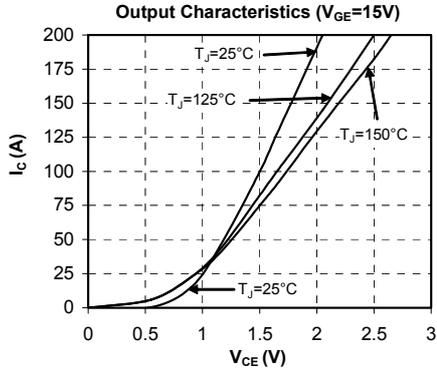
Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$C_{ies}$	Input Capacitance	$V_{GE} = 0\text{V}$		6100		pF
$C_{oes}$	Output Capacitance	$V_{CE} = 25\text{V}$		390		
$C_{res}$	Reverse Transfer Capacitance	$f = 1\text{MHz}$		190		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching ( $25^\circ\text{C}$ ) $V_{GE} = \pm 15\text{V}$ $V_{Bus} = 300\text{V}$ $I_C = 100\text{A}$ $R_G = 3.3\Omega$		115		ns
$T_r$	Rise Time			45		
$T_{d(off)}$	Turn-off Delay Time			225		
$T_f$	Fall Time			55		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching ( $150^\circ\text{C}$ ) $V_{GE} = \pm 15\text{V}$ $V_{Bus} = 300\text{V}$ $I_C = 100\text{A}$ $R_G = 3.3\Omega$		130		ns
$T_r$	Rise Time			50		
$T_{d(off)}$	Turn-off Delay Time			300		
$T_f$	Fall Time			70		
$E_{on}$	Turn on Energy	$V_{GE} = \pm 15\text{V}$ $V_{Bus} = 300\text{V}$ $I_C = 100\text{A}$	$T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	0.4 0.875		mJ
$E_{off}$	Turn off Energy	$R_G = 3.3\Omega$	$T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	2.5 3.5		mJ

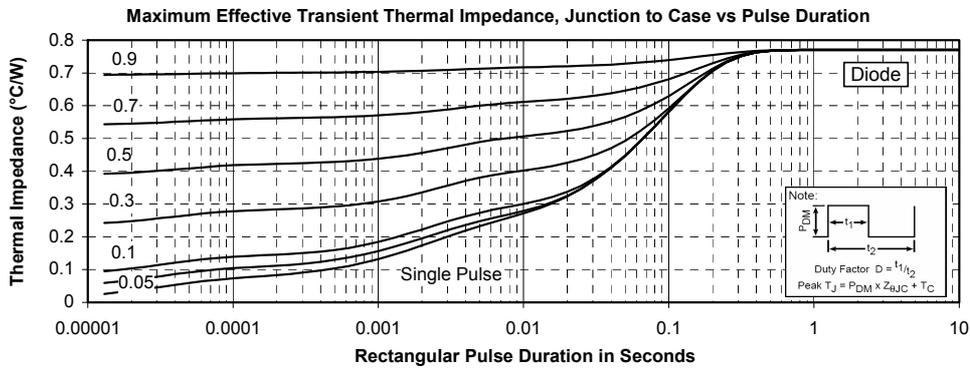
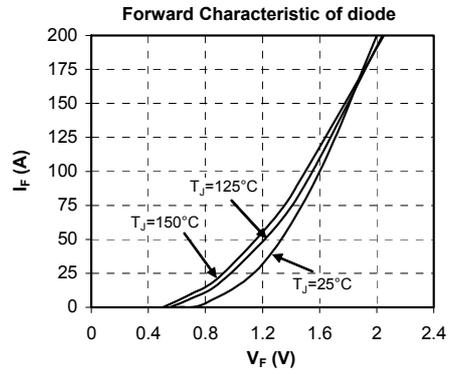
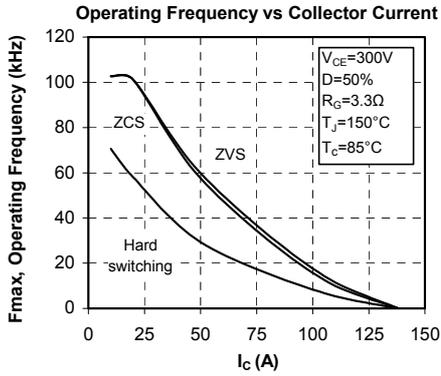
**Diode ratings and characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit	
$V_{RRM}$	Maximum Peak Repetitive Reverse Voltage		600			V	
$I_{RM}$	Maximum Reverse Leakage Current	$V_R = 600\text{V}$			250 500	$\mu\text{A}$	
			$T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$				
$I_F$	DC Forward Current			100		A	
$V_F$	Diode Forward Voltage	$I_F = 100\text{A}$ $V_{GE} = 0\text{V}$		1.6 1.5	2	V	
			$T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$				
$t_{rr}$	Reverse Recovery Time	$I_F = 100\text{A}$ $V_R = 300\text{V}$ $di/dt = 2000\text{A}/\mu\text{s}$		125 220		ns	
$Q_{rr}$	Reverse Recovery Charge				4.7 9.9		$\mu\text{C}$
$E_r$	Reverse Recovery Energy			1.1 2.4		mJ	
			$T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$				



## Typical Performance Curve





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